

HFA45HC60C

Ultrafast, Soft Recovery Diode Thru-Hole (TO-258AA) 600V, 45A

Features

- Dual common cathode configuration
- Reduced RFI and EMI
- Reduced snubbing
- Extensive characterization of recovery parameters
- Hermetic package

Potential Applications

- DC-DC converter
- Motor drives

Product Validation

Qualified according to MIL-PRF-19500 for space applications

Description

HEXFRED[™] diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and di/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motor drives and other applications where switching losses are significant portion of the total losses.

Ordering Information

Table 1 Ordering options

| Part number | Package | Screening Level |
|---------------|----------|-------------------|
| HFA45HC60C | TO-258AA | COTS |
| HFA45HC60CSCV | TO-258AA | JANTXV-equivalent |
| HFA45HC60CSCX | TO-258AA | JANTX-equivalent |
| HFA45HC60CSCS | TO-258AA | S-level |

Product Summary

- V_R (per leg): 600V
- **V**_F: 1.47V
- **Q**_{rr}: 270nC
- **di**(rec)M/dt: 400A/µs



PD-20368B



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1 Absolute Maximum Ratings

| Table 2 | Absolute Maximum Ratings |
|---------|--------------------------|
|---------|--------------------------|

| Symbol | Parameter | Value | Unit |
|-------------------------------|--|----------------|------|
| V _R | Cathode to anode voltage (per leg) | 600 | V |
| I _{F(AV)} | Continuous forward current, T _c = 80°C ¹ | 45 | А |
| I _{FSM} | Single pulse forward current, $T_c = 25^{\circ}C$ (per leg) ² | 225 | А |
| $P_{D} @ T_{C} = 25^{\circ}C$ | Maximum power dissipation | 104 | W |
| TJ T _{STG} | Operating Junction and Storage Temperature Range | -55 to 150 | °C |
| Wt | Weight | 10.9 (Typical) | g |

 $^{^{1}}$ DC = 50% rect. wave

² ½ sine wave, 60 Hz, Pulse width = 8.33 ms



Device Characteristics

2 Device Characteristics

2.1 Electrical Characteristics

Table 3Electrical Characteristics

| Symbol | Parameter | Min. | Тур. | Max. | Unit | Test Conditions |
|----------------|--|------|------|------|------|--|
| V_{BR} | Cathode Anode Breakdown Voltage | 600 | _ | _ | V | I _R = 100μA |
| | Forward Voltage Drop (Per Leg) See Fig. 1 | _ | _ | 1.37 | V | I _F = 22.5A, T _J = -55°C |
| V _F | | _ | _ | 1.47 | V | I _F = 22.5A, T _J = 25°C |
| | | _ | _ | 1.81 | V | I _F = 45A, T _J = 25°C |
| | | _ | _ | 1.37 | V | I _F = 22.5A, T _J = 125°C |
| I _R | Reverse Leakage Current | _ | _ | 10 | μA | $V_R = V_R$ Rated |
| | (Per Leg) See Fig. 2 | _ | _ | 1 | mA | $V_R = V_R$ Rated, $T_J = 125^{\circ}C$ |
| C | Junction Capacitance (Per Leg) See Fig. 3 | _ | _ | 65 | рF | V _R = 200V |
| Ls | Series Inductance (Per Leg) | _ | 8.7 | _ | nH | Measured from anode lead to cathode lead , 6mm (0.025 in) from package |

2.2 Dynamic Recovery Characteristics

Table 4 Dynamic Recovery Characteristics

| Symbol | Parameter | Min. | Тур. | Max. | Unit | Test Condition | S |
|---------------------------------------|---|------|------|------|-------|------------------------------------|--|
| t _{rr} | Reverse Recovery Time (Per Leg) | _ | _ | 97 | ns | $I_{\rm F} = 22A, V_{\rm R} = 200$ |)V, d _{if} /dt = 200A/μs |
| t _{rr1} | Reverse Recovery Time | — | 74 | — | | T _J = 25°C | |
| t _{rr2} | (Per Leg) See Fig. 5 | _ | 194 | — | ns | T _J = 125°C | I _F = 45A |
| I _{RRM1} | Peak Recovery Current | — | 7.5 | — | ^ | T _J = 25°C | |
| I _{RRM2} | (Per Leg) See Fig. 6 | _ | 12 | — | A | T _J = 125°C | $V_{R} = 480V$ |
| Q _{rr1} | Reverse Recovery Charge | — | 270 | — | | T _J = 25°C | |
| Q _{rr2} | (Per Leg) See Fig. 7 | _ | 1210 | _ | nC | T _J = 125°C | $d_{if}/dt = 200 \text{ A}/\mu \text{s}$ |
| di _{(rec)M} /dt ₁ | Peak Rate of Fall of Recovery | _ | 400 | _ | | T _J = 25°C | |
| $di_{(rec)M}/dt_2$ | Current During t₅ (Per Leg) See Fig. 8 | _ | 100 | _ | A/ μs | T _J = 125°C | |

2.3 Thermal-Mechanical Characteristics

Table 5 Thermal-Mechanical Characteristics

| Symbol | Parameter | Тур. | Max. | Unit |
|-----------------|---|------|------|------|
| $R_{\theta JC}$ | Junction to Case, Single Leg Conducting | | 1.2 | °C/W |

Electrical Characteristics Curves





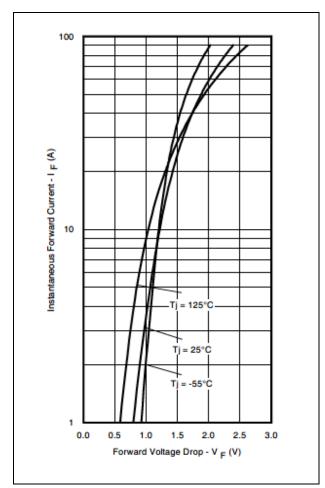
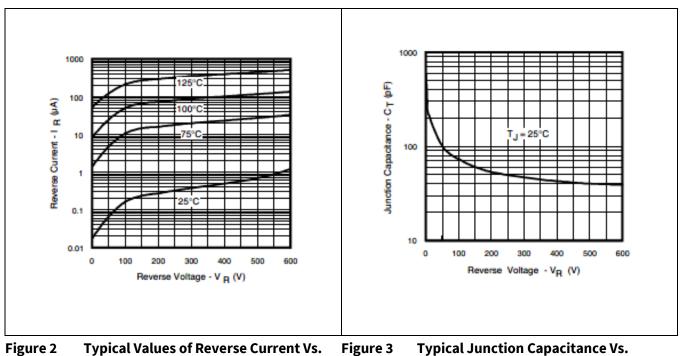
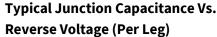


Figure 1 Maximum Forward Voltage Drop Characteristics (Per Leg)



Reverse Voltage (Per Leg)





Electrical Characteristics Curves

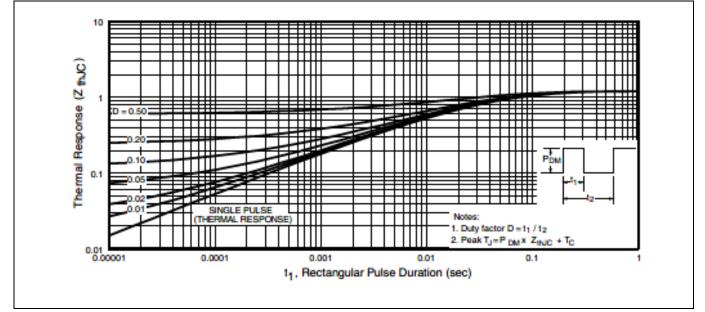


Figure 4 Maximum Thermal Impedance Z_{thJc} Characteristics (Per Leg)

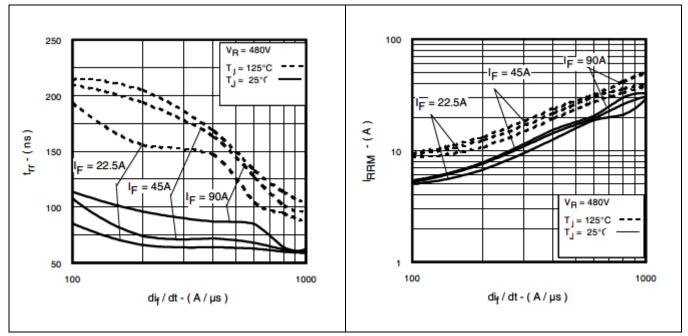
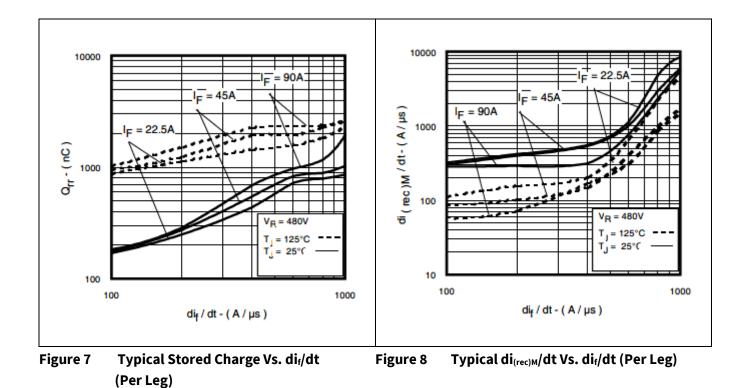


Figure 5 Typical Reverse Recovery Vs. di_f/dt (PerFigure 6 Typ Leg) (Per

Typical Recovery Current Vs. di_f/dt (Per Leg)



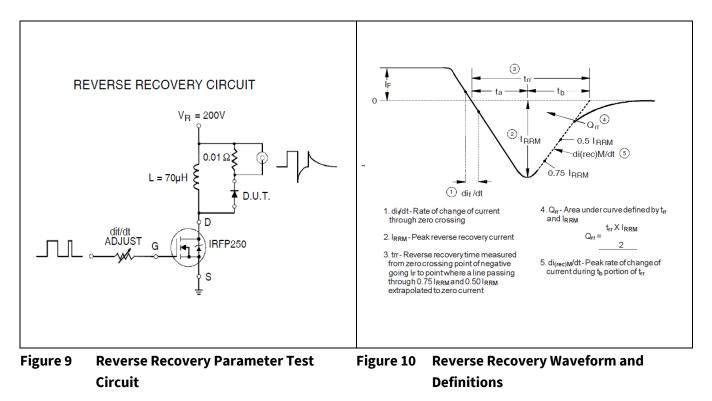
Electrical Characteristics Curves





Test Circuit



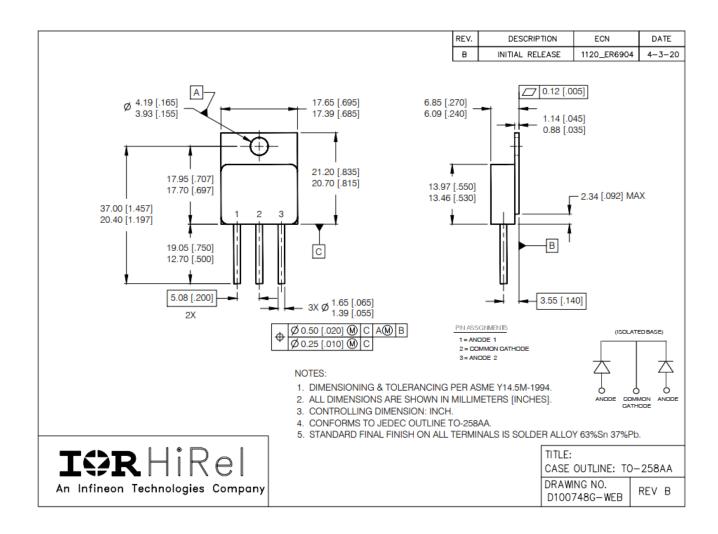




Package Outline

5 Package Outline

Note: For the most updated package outline, please see the website: TO-258AA





Revision history

| Document version | Date of release | Description of changes |
|---------------------|-----------------|----------------------------|
| | 04/17/2001 | Final datasheet (PD-20368) |
| Rev A | 03/07/2013 | Updated per ECN-1120_00911 |
| Rev B | 06/02/2022 | Updated per ECN-1120-08972 |

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